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[^0]
## FPF2411 - IntelliMAX ${ }^{\text {™ }} 6$ V / 6 A - Rated Bi-Directional Switch with Slew Rate Control and RCB

## Features

- Capability: 6 V
- Low Ron
- $\quad 10 \mathrm{~m} \Omega$ at 5 V at PWRA or PWRB (Typ.)
- $\quad 12 \mathrm{~m} \Omega$ at 3.8 V at PWRA or PWRB (Typ.)
- Maximum Current Capability: 6 A (Bi-Directional)
- Ultra-Low $\mathrm{l}_{\mathrm{Q}}:<1 \mu \mathrm{~A}$
- Active LOW Control Pin
- 2 ms Long Slew Rate
- Reverse Current Blocking (RCB) during OFF
- Robust ESD Capability:
- $\quad 5 \mathrm{kV}$ HBM, 2 kV CDM
- 15 kV Air Discharge
- 8 kV Contact Discharge Under IEC 61000-4-2


## Applications

- Smartphone / Tablet PC
- Mobile Devices
- Portable Media Devices


## Description

The FPF2411 is a $6 \mathrm{~V} / 6$ A-rated bi-directional load switch, consisting of a slew-rate-controlled, low-onresistance, P-channel MOSFET switch with protection features. The slew-rate-controlled turn-on characteristic prevents inrush current and the resulting excessive voltage droop on the input power rails. The input voltage range operates from 2.3 V to 5.5 V .
Bi-directional switching allows reverse current from $V_{\text {Out }}$ to $\mathrm{V}_{\mathbb{I}}$. The switching is controlled by active-LOW logic input the ONB pin. The FPF2411 is capable of interfacing directly with low-voltage control signal General-Purpose Input / Output (GPIO).
The FPF2411 is available in 12-bump, 1.235 mm x 1.625 mm Wafer-Level Chip-Scale Package (WLCSP) with 0.4 mm pitch.

## Ordering Information

| Part Number | Top <br> Mark | $R_{\text {ON }}$ (Typ.) <br> at 3.8 V | Output <br> Discharge | ONB Pin <br> Functionality | Package |
| :---: | :---: | :---: | :---: | :---: | :---: |
| FPF2411BUCX_F130 | QR | $12 \mathrm{~m} \Omega$ | No | Active LOW | 12-Ball Wafer-Level Chip-Scale <br> Package (WLCSP), 3 4 4 Array, <br> 0.4 mm Pitch, 250 $\mu \mathrm{m}$ Ball |

## Application Diagrams



Figure 1. High-Level Application Diagrams


Note: Adding a PTVS such as RDP3101B is recommended at PWRB node in order to avoid device damage from surge or equivalent stress.
Figure 2. Battery Isolation Application

## Block Diagrams



Figure 3. Block Diagram

## Application Scenario

Table 1. PWRA and PWRB can be Input or Output, Depending on Scenario

| PWRA | PWRB | ONB | Operations |
| :---: | :---: | :---: | :--- |
| X | X | HIGH | OFF state <br> PWRA and PWRB are isolated. <br> Current more than $I_{\mathrm{sD}}$ or $I_{R C B}$ is NOT allowed. |
| $2.3 \sim 5.5 \mathrm{~V}$ | Open | HIGH $\rightarrow$ LOW | Turn-on with 2 ms of $\mathrm{t}_{\mathrm{R}}$ at PWRB. |
| Open | $2.3 \sim 5.5 \mathrm{~V}$ | HIGH $\rightarrow$ LOW | Turn-on with 2 ms of $\mathrm{t}_{R}$ at PWRA. |
| $2.3 \sim 5.5 \mathrm{~V}$ | Open | LOW | ON state <br> Operating current is from PWRA. <br> No problem with $6 \mathrm{~A} \mathrm{DC} \mathrm{current} \mathrm{flowing}$. |
| Open | $2.3 \sim 5.5 \mathrm{~V}$ | LOW | ON state <br> Operating current is from PWRB. <br> No problem with 6 A DC current flowing. |
| $2.3 \sim 5.5 \mathrm{~V}$ | Open | LOW $\rightarrow$ HIGH | Turn-off with 1 ms of $\mathrm{t}_{\mathrm{F}}$ at PWRB. |
| Open | $2.3 \sim 5.5 \mathrm{~V}$ | LOW $\rightarrow$ HIGH | Turn-off with 1 ms of $\mathrm{t}_{\mathrm{F}}$ at PWRA. |

## Note:

1. $X=$ Don't care.

## Timing Diagrams



Figure 4. Dynamic Behavior

## Pin Configuration



Figure 5. Top View


Figure 6. Bottom View

## Pin Descriptions

| Pin \# | Name | Description |
| :---: | :--- | :--- |
| A2, B2, B4, C2, C4 | PWRA | Power Input / Output: Bi-directional power path |
| A1, A3, B1, B3, C3 | PWRB | Power Input / Output: Bi-directional power path |
| C1 | GND | Ground |
| A4 | ONB | ON/OFF Control Input: Active LOW. |

## Absolute Maximum Ratings

Stresses exceeding the absolute maximum ratings may damage the device. The device may not function or be operable above the recommended operating conditions and stressing the parts to these levels is not recommended. In addition, extended exposure to stresses above the recommended operating conditions may affect device reliability. The absolute maximum ratings are stress ratings only.

| Symbol |  | Parameter | Min. | Max. | Unit |
| :---: | :---: | :---: | :---: | :---: | :---: |
| $\mathrm{V}_{\text {PIN }}$ | PWRA, PWRB, ONB to GND |  | -0.3 | 6.0 | V |
| Isw | Maximum Continuous Switch Current |  |  | 6 | A |
| $t_{\text {PD }}$ | Total Power Dissipation at $\mathrm{T}_{\mathrm{A}}=25^{\circ} \mathrm{C}$ |  |  | 1.48 | W |
| $\mathrm{T}_{J}$ | Operating Junction Temperature |  | -40 | +150 | ${ }^{\circ} \mathrm{C}$ |
| $\mathrm{T}_{\text {STG }}$ | Storage Junction Temperature |  | -65 | +150 | ${ }^{\circ} \mathrm{C}$ |
| $\Theta_{J A}$ | Thermal Resistance, Junction-to-Ambient (1in. ${ }^{2}$ Pad of 2 oz. Copper) |  |  | $84.1^{(2)}$ | ${ }^{\circ} \mathrm{C} / \mathrm{W}$ |
| ESD | Electrostatic Discharge Capability | Human Body Model, JESD22-A114 | 5 |  | kV |
|  |  | Charged Device Model, JESD22-C101 | 2 |  |  |
|  | IEC61000-4-2 System Level | Air Discharge (PWRA, PWRB, ONB to GND) | 15 |  |  |
|  |  | Contact Discharge (PWRA, PWRB, ONB to GND) | 8 |  |  |

## Note:

2. Measured using 2S2P JEDEC std. PCB.

## Recommended Operating Conditions

The Recommended Operating Conditions table defines the conditions for actual device operation. Recommended operating conditions are specified to ensure optimal performance to the datasheet specifications. Fairchild does not recommend exceeding them or designing to Absolute Maximum Ratings.

| Symbol | Parameter | Min. | Max. | Unit |
| :---: | :--- | :---: | :---: | :---: |
| $V_{\text {PWRn }}$ | PWRA, PWRB | 2.3 | 5.5 | V |
| $\mathrm{~T}_{\mathrm{A}}$ | Ambient Operating Temperature | -40 | 85 | ${ }^{\circ} \mathrm{C}$ |

DC / AC Characteristics
Unless otherwise noted, $\mathrm{V}_{\mathbb{I}}=2.3$ to $5.5 \mathrm{~V}, \mathrm{~T}_{\mathrm{A}}=-40$ to $85^{\circ} \mathrm{C}$; typical values are at PWRA or PWRB $=4.2 \mathrm{~V}$ and $\mathrm{T}_{\mathrm{A}}=25^{\circ} \mathrm{C}$.

| Symbol | Parameter | Condition | Min. | Typ. | Max. | Unit |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: |
| VPWRA <br> $V_{\text {PWRB }}$ | Input Voltage |  | 2.3 |  | 5.5 | V |
| ISD | Shutdown Current | PWRA=ONB=5.5 V, PWRB=Open OR <br> PWRB=ONB=5.5 V, PWRA=Open |  |  | 1 | $\mu \mathrm{A}$ |
| IpwRA lpWRB | Quiescent Current | ONB=GND, lout=0 mA |  |  | 1 | $\mu \mathrm{A}$ |
| Ron | On-Resistance | PWRA, PWRB=3.8 V, Iout $=200 \mathrm{~mA}, \mathrm{~T}_{\mathrm{A}}=25^{\circ} \mathrm{C}$ |  | 12 | 17 | $\mathrm{m} \Omega$ |
|  |  | PWRA, PWRB $=5 \mathrm{~V}$, lout $=200 \mathrm{~mA}, \mathrm{~T}_{\mathrm{A}}=25^{\circ} \mathrm{C}$ |  | 10 | 16 |  |
| $\mathrm{V}_{\mathrm{IH}}$ | ONB, Input Logic HIGH Voltage ${ }^{(3)}$ | $\mathrm{PWRn}=4.5 \mathrm{~V}, \mathrm{I}_{\text {LOAD }}=50 \mu \mathrm{~A}, \mathrm{~T}_{\mathrm{A}}($ Max. $)=60^{\circ} \mathrm{C}$ | 4.3 |  |  | V |
|  |  | PWRn=3.6 V, ILOAd $=50 \mu \mathrm{~A}, \mathrm{~T}_{\mathrm{A}}$ (Max.) $=60^{\circ} \mathrm{C}$ | 3.4 |  |  |  |
| VIL | ONB, Input Logic LOW Voltage ${ }^{(3)}$ | PWRn $=4.5 \mathrm{~V}, \mathrm{I}_{\text {LOAD }}=50 \mu \mathrm{~A}, \mathrm{~T}_{\mathrm{A}}($ Max. $)=60^{\circ} \mathrm{C}$ |  |  | 0.4 |  |
|  |  | PWRn=3.6 V, ILOAD $=50 \mu \mathrm{~A}, \mathrm{~T}_{\mathrm{A}}($ Max. $)=60^{\circ} \mathrm{C}$ |  |  | 0.4 |  |
| $\mathrm{R}_{\text {PD }}$ | Pull-Down Resistance at ONB |  |  | 500 | 700 | $\mathrm{k} \Omega$ |

Dynamic Characteristics: see definitions below

| toon | Turn-On Delay ${ }^{(4,5,6)}$ | PWRA or PWRB $=4.2 \mathrm{~V}, \mathrm{R}_{\mathrm{L}}=10 \Omega, \mathrm{C}_{\mathrm{L}}=1 \mu \mathrm{~F}$, ONB=HIGH to LOW | 1.5 | ms |
| :---: | :---: | :---: | :---: | :---: |
| $t_{R}$ | Rise Time ${ }^{(4,5,6)}$ |  | 3.0 |  |
| ton | Turn-On Time ${ }^{(4,5,6)}$ |  | 4.5 |  |
| tooff | Turn-Off Delay ${ }^{(4,5,7)}$ | PWRA or PWRB $=4.2 \mathrm{~V}, \mathrm{R}_{\mathrm{L}}=100 \Omega, \mathrm{C}_{\mathrm{L}}=1 \mu \mathrm{~F}$, ONB=LOW to HIGH | 5.5 | ms |
| $t_{\text {F }}$ | Fall Time ${ }^{(4,5,7)}$ |  | 1.0 |  |
| toff | Turn-Off Time ${ }^{(4,5,7)}$ |  | 6.5 |  |

## Notes:

3. $\mathrm{V}_{\mathrm{IH}} / \mathrm{V}_{\mathrm{IL}}$ is tested under $50 \mu \mathrm{~A}$ current load
4. This parameter is guaranteed by design and characterization; not production tested.
5. $t_{\text {DON }} / t_{\text {DOFF }} / t_{R} / t_{\text {F }}$ are defined in Figure 4.
6. $\mathrm{t}_{\mathrm{ON}}=\mathrm{t}_{\mathrm{R}}+\mathrm{t}_{\mathrm{DON}}$.
7. $\mathrm{t}_{\mathrm{OFF}}=\mathrm{t}_{\mathrm{F}}+\mathrm{t}_{\text {DOFF }}$.

Table 2. $\mathrm{V}_{\mathrm{IH}} / \mathrm{V}_{\mathrm{IL}}[\mathrm{V}]$

| $\mathbf{I}_{\text {LOAD }} \backslash \mathbf{V}_{\mathbf{B A T}}$ | $\mathbf{2 . 7} \mathbf{V}$ | $\mathbf{3 . 7} \mathbf{V}$ | $\mathbf{4 . 3 5} \mathbf{~ V}$ |
| :---: | :---: | :---: | :---: |
| 0.1 mA | $1.8 / 0.7$ | $2.9 / 0.9$ | $3.4 / 1.0$ |
| 1 mA | $1.1 / 0.7$ | $2.1 / 0.9$ | $2.8 / 1.0$ |
| 3 mA | $1.1 / 0.7$ | $2.1 / 0.9$ | $2.7 / 1.0$ |
| 5 mA | $1.0 / 0.7$ | $2.0 / 0.9$ | $2.7 / 1.0$ |
| 10 mA | $0.9 / 0.7$ | $1.9 / 0.8$ | $2.4 / 0.9$ |
| 30 mA | $0.9 / 0.7$ | $1.5 / 0.8$ | $2.2 / 0.9$ |
| 50 mA | $0.9 / 0.7$ | $1.2 / 0.8$ | $1.9 / 0.9$ |
| 100 mA | $0.9 / 0.7$ | $1.0 / 0.8$ | $1.1 / 0.9$ |

## Typical Performance Characteristics



Figure 7. PWRA Quiescent Supply Current vs. Temperature


Figure 9. PWRA Shutdown Supply Current vs. Temperature


Figure 11. Switch On Resistance vs. Temperature


Figure 13. On Resistance vs. PWRB Voltage


Figure 8. PWRB Quiescent Supply Current vs. Temperature


Figure 10. PWRB Shutdown Supply Current vs. Temperature


Figure 12. On Resistance vs. PWRA Voltage


Figure 14. Switch On Time vs. Temperature

Typical Performance Characteristics (Continued)


Figure 15. Switch Off Time vs. Temperature


Figure 16. Turn-On Response $\left(\mathrm{V}_{\mathrm{IN}}=4.2 \mathrm{~V}, \mathrm{C}_{\mathrm{IN}}=1 \mu \mathrm{~F}, \mathrm{C}_{\text {out }}=1 \mu \mathrm{~F}, \mathrm{R}_{\mathrm{L}}=10 \Omega\right.$ )


Figure 17. Turn-OFF Response ( $\mathrm{V}_{\mathrm{IN}}=4.2 \mathrm{~V}, \mathrm{C}_{\mathrm{IN}}=1 \mu \mathrm{~F}, \mathrm{C}_{\text {out }}=1 \mu \mathrm{~F}, \mathrm{R}_{\mathrm{L}}=100 \Omega$ )

## Operation and Application Description

The FPF2411 is an ultra-low-Ron P-channel load switch with bi-directional controlled turn-on and Reverse Current Blocking (RCB). The core is a $12 \mathrm{~m} \Omega \mathrm{P}$-channel MOSFET and controller capable of functioning over a wide input operating range of 2.3 V to 5.5 V . The ONB pin, active-LOW; controls the state of the switch. RCB functionality blocks unwanted reverse current during OFF states by power switch isolation between PWRA and PWRB.

## Inrush Current

Inrush current occurs when the device is turned on. Inrush current is dependent on output capacitance and slew rate control capability, as expressed by:

$$
I_{I N R U S H}=C_{O U T} \times \frac{V_{I N}-V_{\text {INITIAL }}}{t_{R}}+I_{L O A D}
$$

where:
Cout: Output capacitance;
$t_{R}$ : Slew rate or rise time at $V_{\text {out; }}$
$\mathrm{V}_{\mathrm{IN}}$ : Input voltage;
$V_{\text {INitial: }}$ Initial voltage at Cout, usually GND; and load: Load current.

Higher inrush current causes higher input voltage drop, depending on the distributed input resistance and input capacitance. High inrush current can cause problems.

FPF2411 has a 3 ms of slew rate capability under $4.2 \mathrm{~V}_{\mathrm{IN}}$ at $1 \mu \mathrm{~F}$ of $\mathrm{C}_{\text {out }}$ and $10 \Omega$ of $\mathrm{R}_{\mathrm{L}}$. Inrush current can be minimized and no input voltage drop appears, as shown in Figure 16.

## Reverse-Current Blocking

The reverse-current blocking feature protects the input source against current flow from output to input when the load switch is off by changing the internal body diode direction.

## Bypass Capacitor

To limit the voltage drop on the input supply caused by transient inrush current when the switch turns on into a discharged load capacitor; a capacitor must be placed between the PWRA or PWRB and GND pins. A ceramic capacitor of at least $1 \mu \mathrm{~F}$ placed close to the pins is usually sufficient.

## Board Layout

For best performance, all traces should be as short as possible. To be most effective, the input and output capacitors should be placed close to the device to minimize the effect that parasitic trace inductance on normal and short-circuit operation. Using wide traces or large copper planes for all pins (PWRA, PWRB, ONB, and GND) minimizes the parasitic electrical effects and the case-to-ambient thermal impedance.

## WLCSP Packing - Embossed Tape FPF2411BUCX Pin1 at 1 o'clock Rev0

Packing Description:
WLCSP products are classiffed underMoisture Sensitive Level 1 and are packed in moisture barrier bag for added protection.
The carrier tape is made from dissipative polystyrene or polycarbonate resin. The cover tape is a multiayer ilm primarily composed of polyester ilm, adhesive layer, heat activated seaiant, and ant-static sprayed agent. These reeled parts in standac option are shipped with 3000 units per 178 mm ciameter reel. Up to three reels are packed in each intermediate box. The reels is made ofpolydyrene plastic(anti-staticcosted or intrinsic).
These fill reels are individually baroode labeled and placed inside a pizza box made of recydabie corrugated brown paper with a Fairchild logo printing. The reel is packed single reel in the pizza box. And these pizza boxes are placed inside a barcode labeled shipping box which comes in different sizes depending on the number ofparts shipped.


ESD Logo Label sample


F63TNR Label sample


Tape Leader and Trailer Configuration


WLCSP Embossed Tape Dimension


Dimensions are in millimeters

| Package | $\begin{gathered} A_{0} \\ +l-0.05 \end{gathered}$ | $\begin{gathered} \mathrm{Bo} \\ ++-0.05 \end{gathered}$ | $\underset{+0.10}{ }$ | $\begin{array}{\|c\|} \hline D_{1} \\ \text { min. } \\ \hline \end{array}$ | $\underset{+/-0.1}{\mathrm{E}}$ | $\left\lvert\, \begin{gathered} \mathrm{F} \\ +\ldots-0.1 \end{gathered}\right.$ | $\begin{gathered} \mathrm{K}_{0} \\ +l-0.05 \end{gathered}$ | $\begin{array}{r} P_{1} \\ T Y P \end{array}$ | $\begin{aligned} & \text { Po } \\ & \text { TYP } \end{aligned}$ | $\begin{gathered} P_{2} \\ +1-0.05 \end{gathered}$ | $\begin{gathered} \text { TYP } \end{gathered}$ | $\begin{gathered} \text { Tc } \\ +i-0.005 \end{gathered}$ | $\begin{gathered} W \\ +1-0.3 \end{gathered}$ | $\begin{aligned} & \text { Wc } \\ & \text { TYP } \end{aligned}$ |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: |
| FPF2411UCX | 1.55 | 1.95 | 1.50 | 0.5 | 1.75 | 3.5 | 0.75 | 4 | 4 | 2.0 | 0.25 | 0.06 | 8 | 5.3 |

Notes: $A_{0}, B 0$, and Ko dimensionsare determined with respect to the EIA/JEDEC RS-481 rotational and lateral movement requirements(see sketches $A, B$, and $C$ ).


## Physical Dimensions



Figure 18. 12-Ball, 3x4 Array, 0.4 mm Pitch, $250 \mu \mathrm{~m}$ Ball, Wafer-Level Chip-Scale Package (WLCSP)

Nominal Values

| Bump <br> Pitch | Overall Package <br> Height | Silicon <br> Thickness | Solder Bump <br> Height | Solder Bump <br> Diameter |
| :---: | :---: | :---: | :---: | :---: |
| 0.4 mm | 0.586 mm | 0.378 mm | 0.208 mm | 0.260 mm |

## Product-Specific Dimensions

| Product | D | E | $\mathbf{X}$ | $\mathbf{Y}$ |
| :---: | :---: | :---: | :---: | :---: |
| FPF2411BUCX_F130 | 1.235 mm | 1.625 mm | 0.2125 mm | 0.2175 mm |

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